



12500 TI Boulevard, MS 8640, Dallas, Texas 75243

**PCN#20170207002**  
**Qualification of AMKOR P3 as Additional Assembly and Test Site**  
**for Select VSON-CLIP Package Devices**  
**Change Notification / Sample Request**

**Date:** February 13, 2017  
**To:** PREMIER FARNELL PCN

Dear Customer:

This is an announcement of a change to a device that is currently offered by Texas Instruments. The details of this change are on the following pages.

We request you acknowledge receipt of this notification within **30** days of the date of this notice. Lack of acknowledgement of this notice within 30 days constitutes acceptance of the change. If you require samples or additional data to support your evaluation, please request within 30 days.

The proposed first ship date is indicated on page 3 of this notification, unless customer agreement has been reached on an earlier implementation of the change.

This notice does not change the end-of-life status of any product. Should product affected be on a previously issued product withdrawal/discontinuance notice, this notification does not extend the life of that product or change the life time buy offering/discontinuance plan.

For questions regarding this notice, contact your local Field Sales Representative or the PCN Manager ([PCN\\_ww\\_admin\\_team@list.ti.com](mailto:PCN_ww_admin_team@list.ti.com)).

Sincerely,

PCN Team  
SC Business Services

**20170207002**  
**Attachment: 1**

**Products Affected:**

The devices listed on this page are a subset of the complete list of affected devices. According to our records, these are the devices that you have purchased within the past twenty-four (24) months. The corresponding customer part number is also listed, if available.

<b>DEVICE</b>	<b>CUSTOMER PART NUMBER</b>
CSD87335Q3DT	null

Technical details of this Product Change follow on the next page(s).


<b>PCN Number:</b>	20170207002		<b>PCN Date:</b>	Feb 13, 2017													
<b>Title:</b>	Qualification of AMKOR P3 as Additional Assembly and Test Site for Select VSON-CLIP Package Devices																
<b>Customer Contact:</b>	<a href="#">PCN Manager</a>	<b>Dept:</b>	Quality Services														
<b>Proposed 1<sup>st</sup> Ship Date:</b>	May 13, 2017		<b>Estimated Sample Availability:</b>	Date provided at sample request													
<b>Change Type:</b>																	
<input checked="" type="checkbox"/>	Assembly Site	<input type="checkbox"/>	Design	<input type="checkbox"/>	Wafer Bump Site												
<input type="checkbox"/>	Assembly Process	<input type="checkbox"/>	Data Sheet	<input type="checkbox"/>	Wafer Bump Material												
<input checked="" type="checkbox"/>	Assembly Materials	<input type="checkbox"/>	Part number change	<input type="checkbox"/>	Wafer Bump Process												
<input type="checkbox"/>	Mechanical Specification	<input checked="" type="checkbox"/>	Test Site	<input type="checkbox"/>	Wafer Fab Site												
<input type="checkbox"/>	Packing/Shipping/Labeling	<input type="checkbox"/>	Test Process	<input type="checkbox"/>	Wafer Fab Materials												
				<input type="checkbox"/>	Wafer Fab Process												
<b>PCN Details</b>																	
<b>Description of Change:</b>																	
Texas Instruments Incorporated is announcing the qualification of AMKOR P3 as Additional Assembly and Test Site for select devices listed in the "Product Affected" Section. Current assembly sites and Material differences are as follows.																	
<table border="1"> <thead> <tr> <th>Assembly Site</th> <th>Assembly Site Origin</th> <th>Assembly Country Code</th> <th>Assembly Site City</th> </tr> </thead> <tbody> <tr> <td>TI Clark</td> <td>QAB</td> <td>PHL</td> <td>Angeles City, Pampanga</td> </tr> <tr> <td><b>Amkor P3</b></td> <td><b>AP3</b></td> <td><b>PHL</b></td> <td><b>Biñan, Laguna</b></td> </tr> </tbody> </table>						Assembly Site	Assembly Site Origin	Assembly Country Code	Assembly Site City	TI Clark	QAB	PHL	Angeles City, Pampanga	<b>Amkor P3</b>	<b>AP3</b>	<b>PHL</b>	<b>Biñan, Laguna</b>
Assembly Site	Assembly Site Origin	Assembly Country Code	Assembly Site City														
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<b>Material Differences:</b>																	
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	TI Clark	AMKOR P3															
Mold compound	4208625	101390791															
Lead finish	NiPdAu	Matte Sn															
Test coverage, insertions, conditions will remain consistent with current testing and verified with test MQ.																	
<b>Reason for Change:</b>																	
Continuity of supply.																	
<b>Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):</b>																	
None																	
<b>Anticipated impact on Material Declaration</b>																	
<input type="checkbox"/>	No Impact to the Material Declaration	<input checked="" type="checkbox"/>	Material Declarations or Product Content reports are driven from production data and will be available following the production release. Upon production release the revised reports can be obtained from the <a href="#">TI ECO website</a> .														
<b>Changes to product identification resulting from this PCN:</b>																	

Sample product shipping label (not actual product label)

Assembly Site:

TI-CLARK	Assembly Site Origin (22L)	ASO: QAB	ECAT: E4
AMKOR P3	Assembly Site Origin (22L)	ASO: AP3	ECAT: E3


Sample product shipping label to show code location (not actual product label)




MADE IN: Malaysia  
2DC: 2Q:

MSL 2 / 260C / 1 YEAR	SEAL DT
MSL 1 / 235C / UNLIM	03/29/04

OPT:  
ITEM: 39  
LBL: 5A (L)T0:1750





(1P) SN74LS07NSR  
(Q) 2000 (D) 0336  
(31T) LOT: 3959047MLA  
(4W) TKY (1T) 7523483SI2  
(P)  
(2P) REV: (V) 0033317  
(20L) CSO: SHE (21L) CCO: USA  
(22L) ASO: MLA (23L) ACO: MYS

ECAT: E4 = NiPdAu  
ECAT: E3 = Matte Sn

ASSEMBLY SITE CODES: TI-CLARK = I , AP3 = 3

**Product Affected:**

CSD58899Q3D	CSD87333Q3DT	CSD87334Q3DT	CSD87335Q3DT
CSD87333Q3D	CSD87334Q3D	CSD87335Q3D	

## Qualification Report

### Phase 7 Power Block Qual in Amkor P3: CSD87333Q3D, CSD87334Q3D, CSD87335Q3D

Approve Date 06-February-2017

**Product Attributes**

Attributes	Qual Device: CSD87333Q3D	Qual Device: CSD87334Q3D	Qual Device: CSD87335Q3D
Assembly Site	AMKOR P3 A/T PHIL	AMKOR P3 A/T PHIL	AMKOR P3 A/T PHIL
Package Family	DQZ	DQZ	DQZ
Flammability Rating	UL 94 V-0	UL 94 V-0	UL 94 V-0
Wafer Fab Supplier	CFAB	CFAB	CFAB
Wafer Fab Process	NEXFET-LV 30N10	NEXFET-LV 30N10	NEXFET-LV 30N10

- QBS: Qual By Similarity
- Qual Device CSD87333Q3D is qualified at LEVEL1-260C
- Qual Device CSD87335Q3D is qualified at LEVEL1-260C
- Qual Device CSD87334Q3D is qualified at LEVEL1-260C
- Device CSD87333Q3D contains multiple dies.
- Device CSD87334Q3D contains multiple dies.
- Device CSD87335Q3D contains multiple dies

## Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	Test Name / Condition	Duration	Qual Device: CSD87333Q3D	Qual Device: CSD87334Q3D	Qual Device: CSD87335Q3D
MQ	Manufacturability (Assembly)	(per mfg. Site specification)	3/1/0 - Pass	3/1/0 - Pass	3/1/0 - Pass
PC	Preconditioning	(per the appropriate pkg level)	-	3/462/0	3/462/0
TC	**T/C -40C/125C	-40C/+125C (500,1000 Cycles)	-	3/231/0	3/231/0
TC	**T/C -55C/125C	-55C/+125C (500,1000 Cycles)	-	3/231/0	3/231/0

\*\* Preconditioning was performed for Temperature Cycle as applicable

- The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>

Green/Pb-free Status:

Qualified Pb-Free(SMT) and Green

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	<a href="mailto:PCNAmericasContact@list.ti.com">PCNAmericasContact@list.ti.com</a>
Europe	<a href="mailto:PCNEuropeContact@list.ti.com">PCNEuropeContact@list.ti.com</a>
Asia Pacific	<a href="mailto:PCNAsiaContact@list.ti.com">PCNAsiaContact@list.ti.com</a>
Japan	<a href="mailto:PCNJapanContact@list.ti.com">PCNJapanContact@list.ti.com</a>